

N-Ch MOSFET

General Description

The WSF40N06 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF40N06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Absolute Maximum Ratings

Product Summery

BVDSS	RDSON	ID
60V	20mΩ	50A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

TO-252 Pin Configuration





Symbol	Parameter Rating		Units
V _{DS}	Drain-Source Voltage 60		V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	50	A
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	32	A
I₀@T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	10	A
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	8	A
I _{DM}	Pulsed Drain Current ²	200	A
EAS	Single Pulse Avalanche Energy ³	42	mJ
I _{AS}	Avalanche Current	28	A
P₀@T₀=25℃	Total Power Dissipation ⁴	53	W
P _D @T _A =25℃	Total Power Dissipation ⁴ 3.5		W
T _{STG}	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range	-55 to 150	ĉ

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		62	°C /W
R _{ejc}	Thermal Resistance Junction-Case ¹		2	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
$\triangle BV_{DSS} / \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.057		V/℃
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A		20	23	
R _{DS(ON)}		V _{GS} =4.5V , I _D =10A		23	28	mu
V _{GS(th)}	Gate Threshold Voltage		1.2	1.8	2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$-v_{GS} - v_{DS}$, $I_D - 2500A$		-5.68		mV/℃
	Drain Source Lookage Current	V _{DS} =48V , V _{GS} =0V , T _J =25℃			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		9		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	3.4	Ω
Qg	Total Gate Charge (4.5V)			28	36	nC
Q _{gs}	Gate-Source Charge	V _{DS} =30V , V _{GS} =4.5V , I _D =15A		3.5	10	
Q _{gd}	Gate-Drain Charge			6.5	15	
T _{d(on)}	Turn-On Delay Time	V _{DD} =30V , V _{GS} =10V , R _G =3.3Ω, I _D =15A		7.2	14.4	
Tr	Rise Time			38	90	
T _{d(off)}	Turn-Off Delay Time			34	73	ns
T _f	Fall Time			8.2	15.2	
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		1680	2578	
C _{oss}	Output Capacitance			115	203	pF
C _{rss}	Reverse Transfer Capacitance			85	136	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	V _{DD} =25V , L=0.1mH , I _{AS} =15A	19			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,6}	$V_G = V_D = 0V$, Force Current			50	А
I _{SM}	Pulsed Source Current ^{2,6}				200	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1	V
t _{rr}	Reverse Recovery Time	IF=1A ,dI/dt=100A/µs,TJ=25℃		19.6		nS
Q _{rr}	Reverse Recovery Charge			14.2		nC

Note :

1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH,I_{AS}=15A

4.The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ $\,$ junction temperature

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



WSF40N06

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Fig.1 Typical Output Characteristics



Forward Characteristics of Reverse



Fig.5 Normalized $V_{GS(th)}$ v.s T_J



Fig.2 On-Resistance v.s Gate-Source



Fig.4 Gate-Charge Characteristics



Fig.6 Normalized R_{DSON} v.s T_{J}



Fig.9 Normalized Maximum Transient Thermal Impedance







Fig.11 Unclamped Inductive Switching Waveform



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